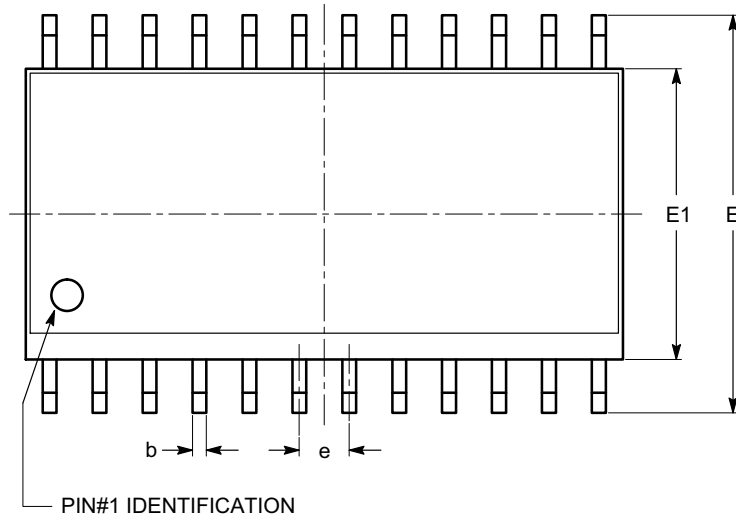


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

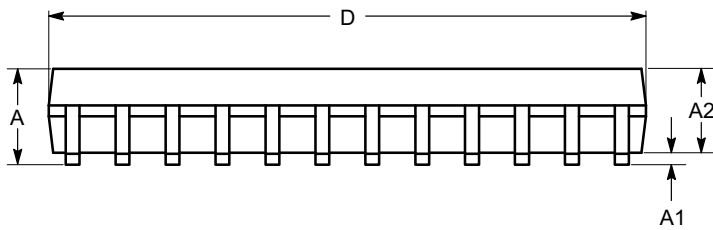
SOIC-24, 300 mils
CASE 751BK-01
ISSUE O

DATE 19 DEC 2008

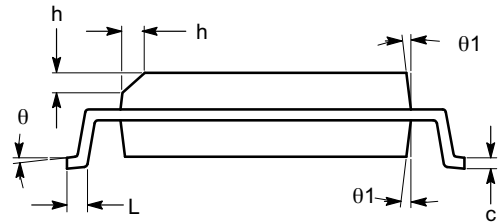


TOP VIEW

SYMBOL	MIN	NOM	MAX
A	2.35		2.65
A1	0.10		0.30
A2	2.05		2.55
b	0.31		0.51
c	0.20		0.33
D	15.20		15.40
E	10.11		10.51
E1	7.34		7.60
e	1.27 BSC		
h	0.25		0.75
L	0.40		1.27
θ	0°		8°
θ_1	5°		15°



SIDE VIEW



END VIEW

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MS-013.

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